•	Member of the Texas Instruments Widebus™ Family		GG PACKA (TOP VIEV	
•	Operates at 2.3 V to 2.7 V for PC1600, PC2100, and PC2700	Q13A [ Q12A [		V <sub>DDQ</sub>
•	Operates at 2.5 V to 2.7 V for PC3200 (QFN Package)	Q11A [ Q10A [	3 62	D13
•	Pinout and Functionality Compatible With JEDEC Standard SSTV16859	Q9A [ V <sub>DDQ</sub> [	5 60	v <sub>cc</sub>
•	600 ps Faster (Simultaneous Switching) Than the JEDEC Standard SSTV16859 in PC2700 DIMM Applications	GND [ Q8A [ Q7A [	7 58 8 57	GND 7 D11 6 D10
•	1-to-2 Outputs to Support Stacked DDR DIMMs	Q6A [ Q5A [	11 54	5 D9 4 GND
•	Output Edge-Control Circuitry Minimizes Switching Noise in an Unterminated Line	Q4A [ Q3A [ Q2A [	13 52	D8 D7 RESET
•	Outputs Meet SSTL_2 Class I Specifications	GND [ Q1A [	15 50	GND GND
•	Supports SSTL_2 Data Inputs  Differential Clock (CLK and CLK) Inputs	Q13B [ V <sub>DDQ</sub> [	1	CLK V <sub>DDQ</sub>
•	Supports LVCMOS Switching Levels on the RESET Input	Q12B [ Q11B [	19 46 20 45	O V <sub>CC</sub>
•	RESET Input Disables Differential Input Receivers, Resets All Registers, and Forces All Outputs Low	Q10B [ Q9B [ Q8B [	22 43	4
•	Pinout Optimizes DIMM PCB Layout	Q7B [ Q6B [	1	D4
•	Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II	GND [ V <sub>DDQ</sub> [	26 39	GND
•	ESD Protection Exceeds JESD 22  – 2000-V Human-Body Model (A114-A)  – 200-V Machine Model (A115-A)	Q5B [ Q4B [	28 37 29 36	7 ] V <sub>CC</sub> 6 ] D2
	- 1000-V Charged-Device Model (C101)	Q3B [ Q2B [ Q1B [	31 34	5
1acc	rintion/ordering information	-		

## description/ordering information

This 13-bit to 26-bit registered buffer is designed for 2.3-V to 2.7-V  $V_{CC}$  operation.

#### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGQ (Tin-Pb Finish)	Tone and real	SN74SSTVF16859SR	SSF859
0°C to 70°C	QFN – RGQ (Matte-Tin Finish)	Tape and reel	SN74SSTVF16859S8	556859
	TSSOP – DGG	Tape and reel	SN74SSTVF16859GR	SSTVF16859

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SCES429B - MARCH 2003 - REVISED FEBRUARY 2004

## description/ordering information (continued)

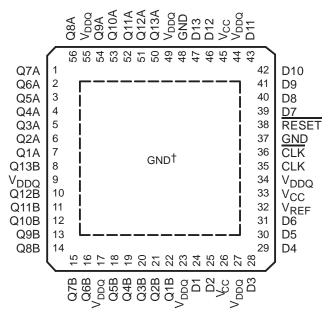
All inputs are SSTL\_2, except the LVCMOS reset (RESET) input. All outputs are edge-controlled LVCMOS circuits optimized for unterminated DIMM loads.

The SN74SSTVF16859 operates from a differential clock (CLK and CLK). Data are registered at the crossing of CLK going high and CLK going low.

The device supports low-power standby operation. When  $\overline{\text{RESET}}$  is low, the differential input receivers are disabled, and undriven (floating) data, clock, and reference voltage ( $V_{\text{REF}}$ ) inputs are allowed. In addition, when  $\overline{\text{RESET}}$  is low, all registers are reset and all outputs are forced low. The LVCMOS  $\overline{\text{RESET}}$  input always must be held at a valid logic high or low level.

To ensure defined outputs from the register before a stable clock has been supplied, RESET must be held in the low state during power up.

#### RGQ PACKAGE (TOP VIEW)



<sup>†</sup>The center die pad must be connected to GND.

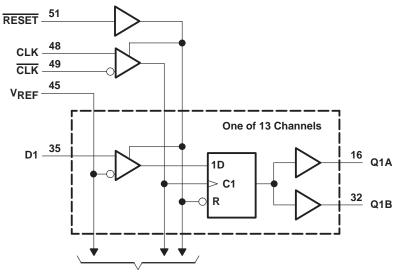
#### **FUNCTION TABLE**

	INPUTS							
RESET	CLK	D	Q					
Н	1	$\downarrow$	Н	Н				
Н	$\uparrow$	$\downarrow$	L	L				
Н	L or H	L or H	Χ	$Q_0$				
L	X or floating	X or floating	X or floating	L				



SCES429B - MARCH 2003 - REVISED FEBRUARY 2004

## logic diagram (positive logic)



To 12 Other Channels

Pin numbers shown are for the DGG package.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> or V <sub>DDQ</sub>	
Input voltage range, V <sub>I</sub> (see Notes 1 and 2)	0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, VO (see Notes 1 and 2)	0.5 V to V <sub>DDQ</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{DDO}$ )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{DDO}$ )	±50 mA
Continuous current through each V <sub>CC</sub> , V <sub>DDQ</sub> , or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	55°C/W
(see Note 4): RGQ package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This value is limited to 3.6 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 4. The package thermal impedance is calculated in accordance with JESD 51-5.



## SN74SSTVF16859 13-BIT TO 26-BIT REGISTERED BUFFER WITH SSTL 2 INPUTS AND OUTPUTS

SCES429B - MARCH 2003 - REVISED FEBRUARY 2004

## recommended operating conditions (see Note 5)

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		$V_{DDQ}$		2.7	V
.,	Output ourselvestiens	PC1600, PC2100, PC2700	2.3		2.7	V
$V_{DDQ}$	Output supply voltage	PC3200	2.5		2.7	V
\/	Deference valtage (\(\lambda_{} \) \(\lambda_{} \)	PC1600, PC2100, PC2700	1.15	1.25	V	
V <sub>REF</sub>	Reference voltage (V <sub>REF</sub> = V <sub>DDQ</sub> /2)	PC3200	1.25	1.3	1.35	V
VI	Input voltage		0		VCC	V
VIH	AC high-level input voltage	Data inputs	V <sub>REF</sub> +310mV			V
V <sub>IL</sub>	AC low-level input voltage	Data inputs			V <sub>REF</sub> -310mV	V
$V_{IH}$	DC high-level input voltage	Data inputs	V <sub>REF</sub> +150mV			V
V <sub>IL</sub>	DC low-level input voltage	Data inputs			V <sub>REF</sub> -150mV	V
VIH	High-level input voltage	RESET	1.7			V
V <sub>IL</sub>	Low-level input voltage	RESET			0.7	V
VICR	Common-mode input voltage range	CLK, CLK	0.97		1.53	V
V <sub>I</sub> (PP)	Peak-to-peak input voltage	CLK, CLK	360			mV
ЮН	High-level output current				-16	
loL	Low-level output current				16	mA
TA	Operating free-air temperature		0		70	°C

NOTE 5: The RESET input of the device must be held at valid logic voltage levels (not floating) to ensure proper device operation. The differential inputs must not be floating unless RESET is low. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## electrical characteristics for PC1600, PC2100, and PC2700 over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		v <sub>cc</sub> †	MIN	TYP‡	MAX	UNIT
٧ıĸ		I <sub>I</sub> = -18 mA		2.3 V			-1.2	V
.,		I <sub>OH</sub> = -100 μA		2.3 V to 2.7 V	V <sub>DDQ</sub> -	0.2		.,,
Vон		$I_{OH} = -8 \text{ mA}$	I <sub>OH</sub> = -8 mA					V
.,		I <sub>OL</sub> = 100 μA		2.3 V to 2.7 V			0.2	V
VOL		I <sub>OL</sub> = 8 mA	2.3 V			0.35	V	
IĮ	All inputs	$V_I = V_{CC}$ or GND		2.7 V			±5	μΑ
	Static standby	RESET = GND	]	0.7.1/			10	μΑ
ICC	Static operating	$\overline{RESET} = V_{CC}, V_I = V_{IH(AC)} \text{ or } V_{IL(AC)}$	IO = 0	2.7 V			25	mA
	Dynamic operating – clock only	RESET = VCC, VI = VIH(AC) or VIL(AC), CLK and CLK switching 50% duty cycle	$RESET = V_{CC}$ , $V_{I} = V_{IH(AC)}$ or $V_{II}$ (AC),			19		μΑ/ MHz
ICCD	Dynamic operating – per each data input	RESET = VCC, VI = VIH(AC) or VIL(AC), CLK and CLK switching 50% duty cycle, One data input switching at one-half clock frequency, 50% duty cycle	IO = 0	2.5 V		7		μΑ/ clock MHz/ D input
	Data inputs	V <sub>I</sub> = V <sub>REF</sub> ± 310 mV			2.5	3	3.5	
C <sub>i</sub> §	CLK, CLK	V <sub>ICR</sub> = 1.25 V, V <sub>I(PP)</sub> = 360mV		2.5 V	2.5	3	3.5	pF
	RESET	V <sub>I</sub> = V <sub>CC</sub> or GND			2.3	3	3.5	

<sup>†</sup> For this test condition, VDDQ always is equal to VCC.



<sup>‡</sup> All typical values are at  $V_{CC} = 2.5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Measured at 50-MHz input frequency

## electrical characteristics for PC3200 over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		v <sub>cc</sub> †	MIN	TYP‡	MAX	UNIT	
VIK		I <sub>I</sub> = -18 mA		2.5 V			-1.2	V	
.,		$I_{OH} = -100 \mu\text{A}$		2.5 V to 2.7 V	V <sub>DDQ</sub> -	-0.2		V	
VOH		$I_{OH} = -8 \text{ mA}$	2.5 V	1.95			V		
.,		I <sub>OL</sub> = 100 μA		2.5 V to 2.7 V			0.2	V	
VOL		I <sub>OL</sub> = 8 mA	2.5 V			0.35	V		
l <sub>l</sub>	All inputs	$V_I = V_{CC}$ or GND		2.7 V			±5	μΑ	
	Static standby	RESET = GND		2.7 V			10	μΑ	
Icc	Static operating	$\overline{RESET} = V_{CC}, V_I = V_{IH(AC)} \text{ or } V_{IL(AC)}$	IO = 0	2.7 V			25	mA	
	Dynamic operating – clock only	RESET = VCC, VI = VIH(AC) or VIL(AC), CLK and CLK switching 50% duty cycle				19		μΑ/ MHz	
ICCD	Dynamic operating – per each data input	RESET = VCC, VI = VIH(AC) or VIL(AC), CLK and CLK switching 50% duty cycle, One data input switching at one-half clock frequency, 50% duty cycle	IO = 0	2.6 V		7		μΑ/ clock MHz/ D input	
	Data inputs	$V_I = V_{REF} \pm 310 \text{ mV}$		2.5	3	3.5			
C <sub>i</sub> §	CLK, CLK	V <sub>ICR</sub> = 1.25 V, V <sub>I(PP)</sub> = 360mV		2.6 V	2.5	3	3.5	pF	
	RESET	$V_I = V_{CC}$ or GND			2.3	3	3.5		

 $<sup>^{\</sup>dagger}$  For this test condition,  $V_{\mbox{\scriptsize DDQ}}$  always is equal to  $V_{\mbox{\scriptsize CC}}.$ 

## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				V <sub>CC</sub> =		V <sub>CC</sub> =	2.6 V V†	UNIT	
				MIN	MAX	MIN	MAX		
fclock	Clock frequency				500		500	MHz	
t <sub>W</sub>	Pulse duration, CL	1		1		ns			
tact	Differential inputs a		22		22	ns			
tinact	Differential inputs in	nactive time (see Note 7)			22		22	ns	
	Outro Cara	Fast slew rate (see Notes 8 and 10)	D	0.65		0.65			
t <sub>su</sub>	Setup time	Slow slew rate (see Notes 9 and 10)	Data before CLK↑, CLK↓	0.75		0.75		ns	
4.	Hald Care	Fast slew rate (see Notes 8 and 10)	Data after CLK↑, CLK↓	0.65		0.65			
th	Hold time	Slow slew rate (see Notes 9 and 10)	Data after CLK↑, CLK↓	0.8		0.8		ns	

† For this test condition, V<sub>DDQ</sub> always is equal to V<sub>CC</sub>.

NOTES: 6. V<sub>REF</sub> must be held at a valid input level, and data inputs must be held low for a minimum time of t<sub>act</sub> max, after RESET is taken high.

- 8. For data signal input slew rate ≥1 V/ns.
- 9. For data signal input slew rate ≥0.5 V/ns and <1 V/ns.
- 10. CLK, CLK signals input slew rates are ≥1 V/ns.



<sup>‡</sup> All typical values are at  $V_{CC} = 2.6 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Measured at 50-MHz input frequency

<sup>7.</sup> VREF, data, and clock inputs must be held at valid voltage levels (not floating) for a minimum time of t<sub>inact</sub> max, after RESET is taken

## SN74SSTVF16859 13-BIT TO 26-BIT REGISTERED BUFFER WITH SSTL 2 INPUTS AND OUTPUTS

SCES429B - MARCH 2003 - REVISED FEBRUARY 2004

## switching characteristics for TSSOP over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V <sub>CC</sub> = ± 0.2	UNIT	
	(INPOT)	(OUTPUT)	MIN	MAX	
f <sub>max</sub>			500		MHz
t <sub>pd</sub> ‡	CLK and CLK	Q	1.1	2.5	ns
t <sub>PHL</sub>	RESET	Q		5	ns

<sup>†</sup> For this test condition, V<sub>DDQ</sub> always is equal to V<sub>CC</sub>.

## switching characteristics for QFN over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V <sub>CC</sub> = ± 0.2	2.5 V V <sup>†</sup>	V <sub>CC</sub> = ± 0.1	UNIT	
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
f <sub>max</sub>			500		500		MHz
t <sub>pd</sub> ‡	CLK and CLK	Q	1.1	2.5	1.1	2.2	ns
t <sub>PHL</sub>	RESET	Q		5		5	ns

<sup>†</sup> For this test condition, VDDQ always is equal to VCC.

## output slew rates over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	V <sub>CC</sub> = ± 0.2	2.5 V 2 V†	V <sub>CC</sub> = ± 0.1	2.6 V V†	UNIT
			MIN	MAX	MIN	MAX	
dV/dt_r	20%	80%	1	4	1	4	V/ns
dV/dt_f	80%	20%	1	4	1	4	V/ns
dV/dt_Δ§	20% or 80%	80% or 20%		1		1	V/ns

<sup>†</sup> For this test condition, VDDQ always is equal to VCC.

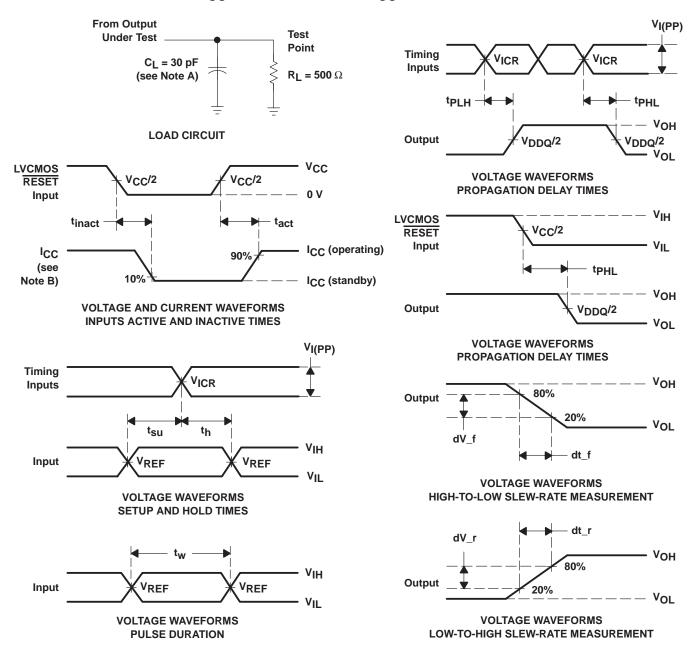


<sup>‡</sup> Single-bit switching

<sup>&</sup>lt;sup>‡</sup> Single-bit switching

<sup>§</sup> Difference between dV/dt\_r (rising edge rate) and dV/dt\_f (falling edge rate).

# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.5 V $\pm$ 0.2 V AND $V_{CC}$ = 2.6 V $\pm$ 0.1 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B.  $I_{CC}$  tested with clock and data inputs held at  $V_{CC}$  or GND, and  $I_{O} = 0$  mA.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , input slew rate = 1 V/ns  $\pm$ 20% (unless otherwise noted).
- D. The outputs are measured one at a time, with one transition per measurement.
- E. VTT = VREF = VDDQ/2
- F. V<sub>IH</sub> = V<sub>REF</sub> + 310 mV (ac voltage levels) for differential inputs. V<sub>IH</sub> = V<sub>CC</sub> for LVCMOS input.
- G.  $V_{IL} = V_{REF} 310$  mV (ac voltage levels) for differential inputs.  $V_{IL} = GND$  for LVCMOS input.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







.com 9-Nov-2007

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74SSTVF16859G4RG4	ACTIVE	QFN	RGQ	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR
SN74SSTVF16859G4R	ACTIVE	QFN	RGQ	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-3-260C-168 HR
SN74SSTVF16859GR	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74SSTVF16859GRG4	ACTIVE	TSSOP	DGG	64	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74SSTVF16859S8	ACTIVE	QFN	RGQ	56	2000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
SN74SSTVF16859S8G3	ACTIVE	QFN	RGQ	56	2000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
SN74SSTVF16859SR	ACTIVE	QFN	RGQ	56	2000	TBD	CU SNPB	Level-3-235C-168 HR
SN74SSTVF16859SRG3	ACTIVE	QFN	RGQ	56		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

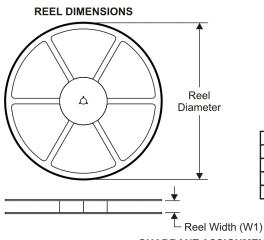
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

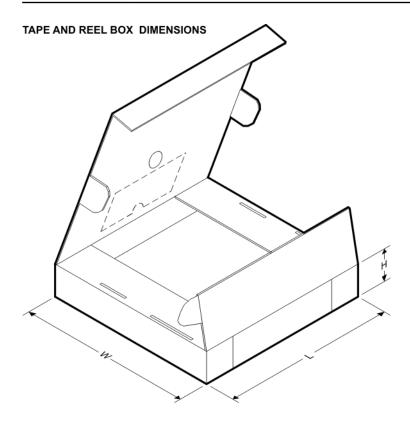
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74SSTVF16859GR	TSSOP	DGG	64	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1





#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74SSTVF16859GR	TSSOP	DGG	64	2000	346.0	346.0	41.0

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

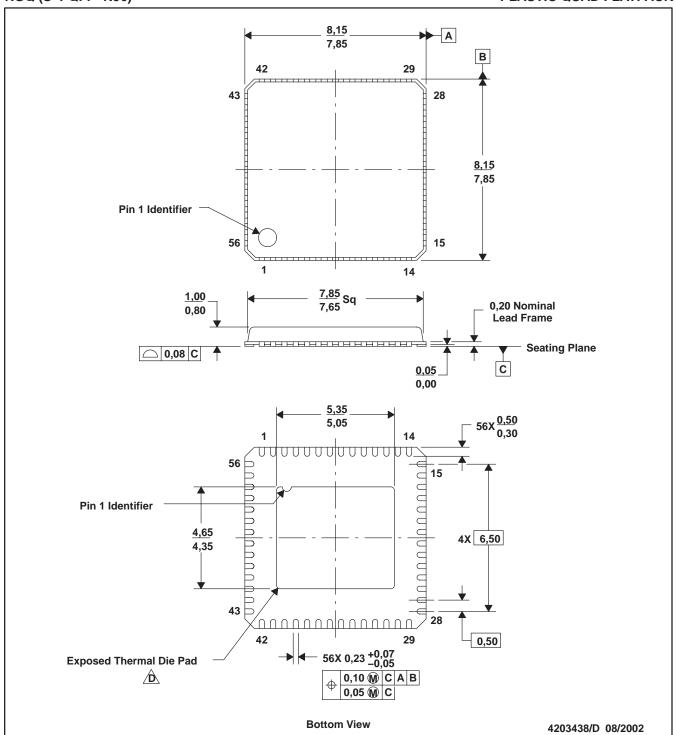
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

## RGQ (S-PQFP-N56)

#### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. QFN (Quad Flatpack No-Lead) Package configuration.

The Package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad may be electrically connected to ground.

E. Package registration with JEDEC MO-220 variation VLLD-2.



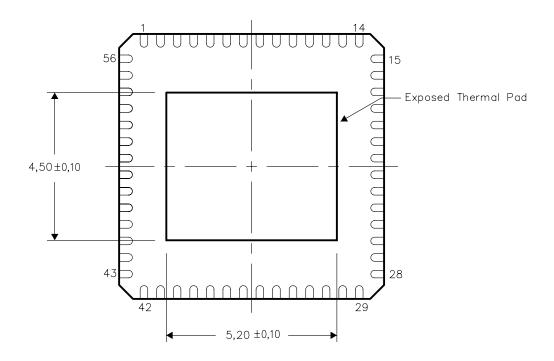


#### THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No—Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No—Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

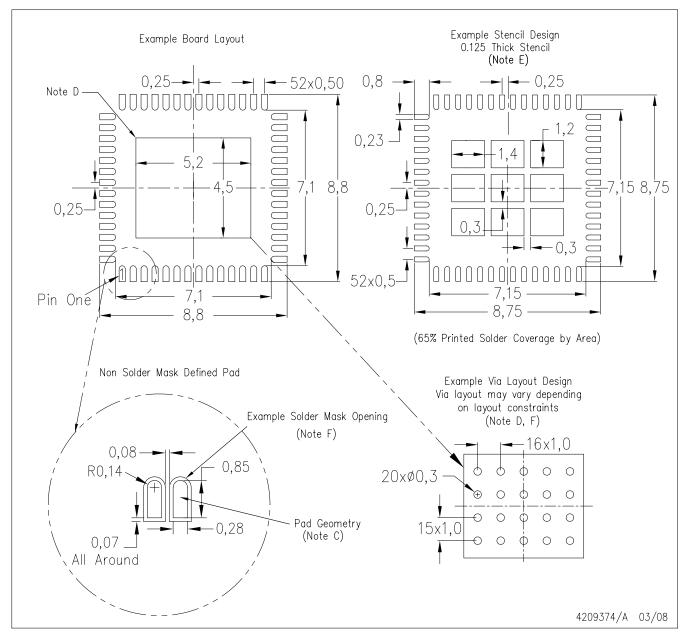


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

## RGQ (S-PVQFN-N56)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat—Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <a href="http://www.ti.com">http://www.ti.com</a>>.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.



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